

Title (en)  
HEAT SINK, AND ASSEMBLY OR MODULE UNIT COMPRISING A HEAT SINK

Title (de)  
WÄRMESENKE SOWIE BAU- ODER MODULEINHEIT MIT EINER WÄRMESENKE

Title (fr)  
PUITS DE CHALEUR ET MODULE OU UNITE MODULAIRE PRESENTANT UN Puits DE CHALEUR

Publication  
**EP 2132772 A2 20091216 (DE)**

Application  
**EP 07846389 A 20071204**

Priority  

- DE 2007002186 W 20071204
- DE 102007015771 A 20070330
- DE 102007027991 A 20070614
- DE 102007030389 A 20070629

Abstract (en)  
[origin: WO2008119309A2] Disclosed is a heat sink for cooling parts, subassemblies, modules, or similar components, particularly for cooling electrical or electronic components. Said heat sink comprises at least one cooling element which forms at least one cooling area for connecting the component that is to be cooled and which is made of a metallic material in said cooling area.

IPC 8 full level  
**H01L 23/373** (2006.01); **H01S 5/024** (2006.01)

CPC (source: EP US)  
**H01L 23/3735** (2013.01 - EP US); **H01S 5/02476** (2013.01 - EP US); **H05K 7/20481** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/73** (2013.01 - EP US); **H01L 25/072** (2013.01 - EP US); **H01L 25/18** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48137** (2013.01 - EP US); **H01L 2224/48139** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/48472** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/0102** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01322** (2013.01 - EP US); **H01L 2924/13055** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01S 5/0237** (2021.01 - EP US); **H01S 5/02423** (2013.01 - EP US); **H01S 5/02469** (2013.01 - EP US); **H01S 5/4025** (2013.01 - EP US); **H05K 1/0306** (2013.01 - EP); **H05K 3/0061** (2013.01 - EP)

C-Set (source: EP US)

EP  

1. **H01L 2224/48472 + H01L 2224/48227 + H01L 2924/00**
2. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00012**
3. **H01L 2224/48091 + H01L 2924/00014**
4. **H01L 2224/48472 + H01L 2224/48091 + H01L 2924/00**
5. **H01L 2924/00014 + H01L 2224/45099**
6. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**
7. **H01L 2924/181 + H01L 2924/00012**

US  

1. **H01L 2224/48472 + H01L 2224/48227 + H01L 2924/00**
2. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00012**
3. **H01L 2224/48091 + H01L 2924/00014**
4. **H01L 2224/48472 + H01L 2224/48091 + H01L 2924/00**
5. **H01L 2924/00014 + H01L 2224/45099**
6. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**
7. **H01L 2924/181 + H01L 2924/00**

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**DE 102007030389 A1 20081002**; **DE 102007030389 B4 20150813**; CN 101641786 A 20100203; CN 101641786 B 20121212; EP 2132772 A2 20091216; JP 2010522974 A 20100708; JP 5429819 B2 20140226; US 2010290490 A1 20101118; US 8559475 B2 20131015; WO 2008119309 A2 20081009; WO 2008119309 A3 20090219

DOCDB simple family (application)  
**DE 102007030389 A 20070629**; CN 200780052443 A 20071204; DE 2007002186 W 20071204; EP 07846389 A 20071204; JP 2010500059 A 20071204; US 45050507 A 20071204